PK091 (v1.5) May 13, 2016

100% Material Declaration Data Sheet for FFG672

Average Weight : 6.5119 g

Component	Substance Description	CAS # or Description	% of Component	Use in product	Component Weight	Component % of total
Silicon Die					**0.458097**	**7.035%**
	Si	7440-21-3	100.000	basis	0.458097	
Solder Bump					**0.024729**	**0.380%**
	Sn	7440-31-5	63.000	basis	0.015580	
	Pb	7439-92-1	37.000	basis	0.009150	
Solder Paste					**0.048000**	**0.737%**
	Sn	7440-31-5	96.500	metal	0.046320	
	Ag	7440-22-4	3.000	metal	0.001440	
	Cu	7440-50-8	0.500	metal	0.000240	
Capacitor 1					**0.016000**	**0.246%**
	Barium titanium trioxide	12047-27-7	51.100	Ceramic	0.008176	
	Copper	7440-50-8	16.900	Inner electrode	0.002704	
	Nickel	7440-02-0	27.000	Out electrode	0.004320	
	Nickel	7440-02-0	2.000	Plating1	0.000320	
	Tin	7440-31-5	3.000	Plating2	0.000480	
Underfill					**0.056000**	**0.860%**
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.000	basis	0.011200	
	Phenolic resin	trade secret	15.000	basis	0.008400	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.000	basis	0.002800	
	Amine type accelerator	trade secret	5.000	basis	0.002800	
	Silicon dioxide	60676-86-0	51.500	basis	0.028840	
	Carbon black	1333-86-4	1.000	basis	0.000560	
	Additives	trade secret	2.500	Additive	0.001400	
Lid					**3.040000**	**46.684%**
	Cu	7440-50-8	99.450	Main material	3.023280	
	Ni	8049-31-8	0.550	Main material	0.016720	
Lid Adhesive					**0.106000**	**1.628%**
	Aluminum oxide(Al2O3)	1344-28-1	70.000	Main material	0.074200	
	Zinc oxide (ZnO)	1314-13-2	15.000	Main material	0.015900	
	Silicone	Trade Secret	15.000	Main material	0.015900	
Solder Ball					**0.562885**	**8.644%**
	Sn	7440-31-5	95.500	Main material	0.537555	
	Ag	7440-22-4	4.000	Main material	0.022515	
	Cu	7440-50-8	0.500	Main material	0.002814	
Substrate					**2.200189**	**33.787%**
	Copper	7440-50-8	52.18	Main material	1.148059	
	Tin	7440-31-5	0.91	Main material	0.020022	
	Lead	7439-92-1	0.21	Main material	0.004620	
	Silver	7440-22-4	0.02	Main material	0.000440	
	Core	N/A	28.49	Main material	0.626834	
	ABF	N/A	15.26	Main material	0.335749	
	Solder Mask	N/A	2.93	Main material	0.064466	

Revision History

Date	Version	Description of Revisions
03/14/2006	1.0	Initial Initial release.
08/11/2006	1.1	100% Material Declaration.
09/27/2006	1.2	Updated component descriptions.
07/20/2010	1.3	Updated Heat Spreader substance description
04/08/2011	1.4	Updated component descriptions and weights
05/13/2016	1.5	Updated substrate

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